

IN THE SPECIFICATION:

Page 1, line 2, please amend the paragraph as follows:

The present invention relates to a mold die and to a method of manufacture of a semiconductor device using the mold die; and, more particularly, the invention relates to a technology in which a die is used effectively for sealing a semiconductor chip, which is mounted on a wiring board via an elastic material and an opening of the wiring-board, by transfer mold processing.